

TSMC-03-179



January 22, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/718,191 11/20/03 |
Hsin-Hui Lee et al.
A NOVEL ENCAPSULATION METHOD
FOR SBGA
| _____ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

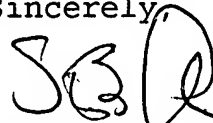
Signature/Date SB Ackerman 1/27/04

U.S. Patent 6,537,482 to Farnworth, "Underfill and Encapsulation of Carrier Substrate-Mounted Flip-Chip Components Using Stereolithography," teaches encapsulating the die with a resin.

The following two U.S. Patents disclose conventional encapsulation methods:

- 1) U.S. Patent 6,127,724 to DiStefano, "Packaged Micro-electronic Elements with Enhanced Thermal Conduction."
- 2) U.S. Patent 6,020,218 to Shim et al., "Method of Manufacturing Ball Grid Array Semiconductor Package."

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a long horizontal flourish extending to the right.

Stephen B. Ackerman,
Reg. No. 37761

Application Number

10/718, 191

Hsin-Hui Lee et al.

11/20/03

Group Art Unit

(Use several shouts if necessary)

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

[illegible]

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.



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ASSOCIATE POWER OF ATTORNEY

I hereby appoint Rosemary L.S. Pike, registration number 39,332, as my associate attorney in this case. Her telephone number is (765) 453-0866.

Please continue to direct all correspondence in this case to the undersigned attorney.

Respectfully submitted,

Stephen B. Ackerman,

Principal attorney of record